



Material Content Data Sheet



Sales Product Name	SPD04P10P G	Issued	19. March 2021
MA#	MA000442448		
Package	PG-TO252-3-311	Weight*	313.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.091	0.35	0.35	3486	3486
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		458	
	non noble metal	copper	7440-50-8	143.098	45.71	45.77	457091	457686
wire	non noble metal	aluminium	7429-90-5	0.728	0.23	0.23	2326	2326
encapsulation	inorganic material	antimonytrioxide	1309-64-4	2.011	0.64		6425	
	plastics	brominated resin	-	2.155	0.69		6884	
	organic material	carbon black	1333-86-4	2.299	0.73		7343	
	plastics	epoxy resin	-	19.396	6.20		61955	
	inorganic material	silicondioxide	60676-86-0	117.811	37.63	45.89	376318	458925
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11947	11947
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277
solder	non noble metal	tin	7440-31-5	0.025	0.01		80	
	noble metal	silver	7440-22-4	0.031	0.01		100	
	non noble metal	lead	7439-92-1	1.201	0.38	0.40	3837	4017
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.13	6.14	61257	61336
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com